

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Weibo YU	10/06/2011
Hsueh-Chin LU	10/13/2011
Han-Guan CHEW	10/28/2011
Kuo Bin HUANG	10/25/2011
Chao-Cheng CHEN	10/06/2011
Syun-Ming JANG	10/06/2011
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13244337
CORRESPONDENCE DATA	
Fax Number:	(214)200-0853
Phone:	214-651-5000
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
Correspondent Name:	HAYNES AND BOONE, LLP IP Section
Address Line 1:	2323 Victory Avenue
Address Line 2:	Suite 700
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OP \$40.00 13244337

ATTORNEY DOCKET NUMBER:	2010-0486/24061.1828
NAME OF SUBMITTER:	David M. O'Dell
Total Attachments: 6 source=1828_assignment#page1.tif source=1828_assignment#page2.tif source=1828_assignment#page3.tif source=1828_assignment#page4.tif source=1828_assignment#page5.tif source=1828_assignment#page6.tif	

A S S I G N M E N T

WHEREAS, we,

- | | | | |
|-----|-----------------|----|---|
| (1) | Weibo Yu | of | Block 516, #12-157, Woodlands Drive 16
Singapore 730516 |
| (2) | Hsueh-Chin Lu | of | No. 235-46 Chun-Hua Road
Hsinchu City, Taiwan, R.O.C. |
| (3) | Han-Guan Chew | of | Block 691A Choa Chu Kang, Crescent #10-34
Singapore 681691 |
| (4) | Kuo Bin Huang | of | 4F, No. 72, Zihciang N. Road
Jhubei City, Hsinchu County 302, Taiwan, R.O.C. |
| (5) | Chao-Cheng Chen | of | #46 3F-2, Lui-Sui Road
Shin-Chu City, Taiwan, R.O.C. |
| (6) | Syun-Ming Jang | of | 7F, 83 N. Kuan-Hua Street
Hsin-Chu, Taiwan, R.O.C. |

have invented certain improvements in

SILICON NITRIDE ETCHING IN A SINGLE WAFER APPARATUS

for which we have executed an application for Letters Patent of the United States of America,

 X of even date filed herewith; and
 xx filed on 09-24-2011 and assigned application number 13/244,337; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries

foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.


AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Weibo Yu

Residence Address: Block 516, #12-157, Woodlands Drive 16
Singapore 730516


Dated: 10/6/2011


Inventor Signature

Inventor Name: Hsueh-Chin Lu

Residence Address: No. 233-46 Chun-Hua Road
Hsinchu City, Taiwan, R.O.C.

Dated: 10/13/2011


Inventor Signature

Inventor Name: Han-Guan Chew

Residence Address: Block 691A Choa Chu Kang, Crescent #10-34
Singapore 681691.

Dated: _____

Inventor Signature

Inventor Name: Kuo Bin Huang
Residence Address: 4F, No. 72, Zihciang N. Road
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Dated: 10/25/2011 Kuo Bin Huang
Inventor Signature

Inventor Name: Chao-Cheng Chen
Residence Address: #46 3F-2, Lui-Sui Road
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Dated: 10/6/2011 Chao-Cheng Chen
Inventor Signature

Inventor Name: Syun-Ming Jang
Residence Address: 7F, 83 N. Kuan-Hua Street
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Dated: 10/6/2011 Syun-Ming Jang
Inventor Signature

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foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

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Inventor Name: Weibo Yu
Residence Address: Block 516, #12-157, Woodlands Drive 16
Singapore 730516

Dated: _____
Inventor Signature

Inventor Name: Hsueh-Chin Lu
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Dated: _____
Inventor Signature

Inventor Name: Han-Guan Chew
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Dated: 28th Oct 2011 
Inventor Signature

Inventor Name: Kuo Bin Huang
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Dated: _____
Inventor Signature _____

Inventor Name: Chao-Cheng Chen
Residence Address: #46 3F-2, Lui-Sui Road
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Dated: _____
Inventor Signature _____

Inventor Name: Syun-Ming Jang
Residence Address: 7F, 83 N. Kuan-Hua Street
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Dated: _____
Inventor Signature _____
